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October 15, 2003

Customer No.
23911

Mail Stop Patent Application
Director of the United States
Patent and Trademark Office
P.O. Box 1450
Alexandria, VA 22313-1450

Re: New U.S. Patent Appln.
Our Ref: 056203.52845US

Sir:

Transmitted herewith for filing is the patent application of:

Koki ISHIZAKI and Takeshi SHIRATO

entitled: **THE MULTILAYER ELECTRONIC SUBSTRATE, AND THE METHOD
OF MANUFACTURING MULTILAYER ELECTRONIC SUBSTRATE**

Enclosed are:

1. Specification, including 15 claims and Abstract of the Disclosure (46 pages, and title page).
2. 8 Sheets of Formal drawings showing Figs. 1-2, 3A-3F, 4A-4G, and 5-8.
3. Preliminary Amendment.
4. Information Disclosure Statement & Form PTO-1449 with 1 reference.

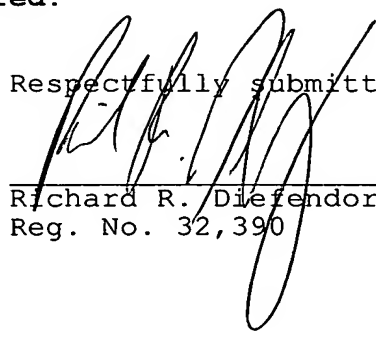
Priority is being claimed under 35 U.S.C. §119 and 37 C.F.R. §1.55 based on Priority Document 2002-302229, filed in Japan on October 16, 2002.

The filing fee has been calculated as shown below:

Basic Fee					\$385/770 = \$770.00
Total Claims	<u>15</u>	- 20	=	<u>0</u>	x \$ 9/18 = \$
Independent Claims	<u>3</u>	- 3	=	<u>0</u>	x \$43/86 = \$
Multiple Dependent Claim Presented					\$145/290 = \$
Total Filing Fee					<u>\$770.00</u>

The filing fee is being deferred.

Respectfully submitted,


Richard R. Diefendorf
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RRD:msy